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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	18
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f677-e-ss

Device	Program Memory	Data Memory		I/O	10-bit A/D (ch)	Comparators	Timers 8/16-bit	SSP	ECCP+	EUSART
	Flash (words)	SRAM (bytes)	EEPROM (bytes)							
PIC16F631	1024	64	128	18	—	2	1/1	No	No	No
PIC16F677	2048	128	256	18	12	2	1/1	Yes	No	No
PIC16F685	4096	256	256	18	12	2	2/1	No	Yes	No
PIC16F687	2048	128	256	18	12	2	1/1	Yes	No	Yes
PIC16F689	4096	256	256	18	12	2	1/1	Yes	No	Yes
PIC16F690	4096	256	256	18	12	2	2/1	Yes	Yes	Yes

PIC16F631 Pin Diagram

20-pin PDIP, SOIC, SSOP

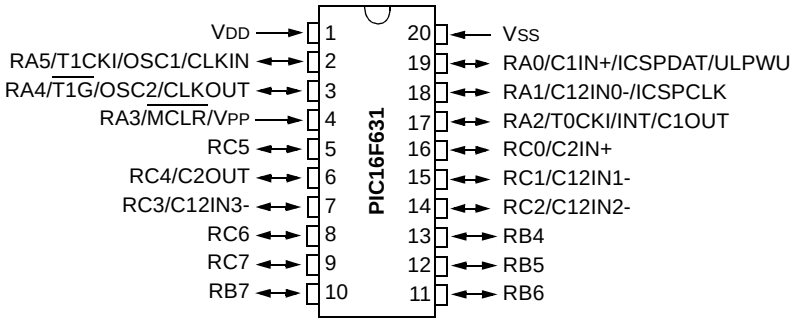


TABLE 1: PIC16F631 PIN SUMMARY

I/O	Pin	Analog	Comparators	Timers	Interrupt	Pull-up	Basic
RA0	19	AN0/ULPWU	C1IN+	—	IOC	Y	ICSPDAT
RA1	18	AN1	C12IN0-	—	IOC	Y	ICSPCLK
RA2	17	—	C1OUT	T0CKI	IOC/INT	Y	—
RA3	4	—	—	—	IOC	Y(1)	MCLR/VPP
RA4	3	—	—	T1G	IOC	Y	OSC2/CLKOUT
RA5	2	—	—	T1CKI	IOC	Y	OSC1/CLKIN
RB4	13	—	—	—	IOC	Y	—
RB5	12	—	—	—	IOC	Y	—
RB6	11	—	—	—	IOC	Y	—
RB7	10	—	—	—	IOC	Y	—
RC0	16	AN4	C2IN+	—	—	—	—
RC1	15	AN5	C12IN1-	—	—	—	—
RC2	14	AN6	C12IN2-	—	—	—	—
RC3	7	AN7	C12IN3-	—	—	—	—
RC4	6	—	C2OUT	—	—	—	—
RC5	5	—	—	—	—	—	—
RC6	8	—	—	—	—	—	—
RC7	9	—	—	—	—	—	—
—	1	—	—	—	—	—	VDD
—	20	—	—	—	—	—	VSS

Note 1: Pull-up enabled only with external MCLR configuration.

FIGURE 1-3: PIC16F685 BLOCK DIAGRAM

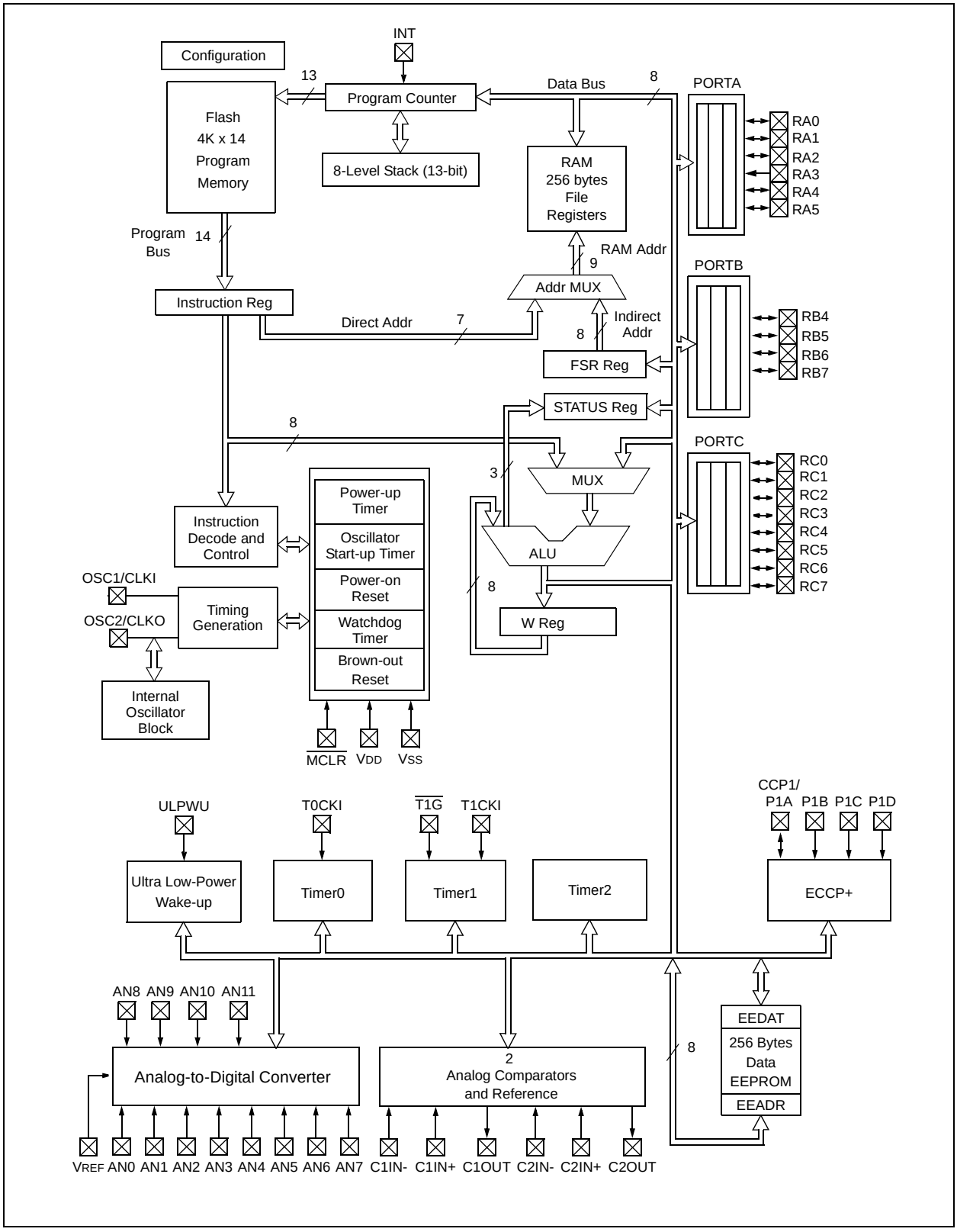


TABLE 1-3: PINOUT DESCRIPTION – PIC16F685

Name	Function	Input Type	Output Type	Description
RA0/AN0/C1IN+/ICSPDAT/ ULPWU	RA0	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN0	AN	—	A/D Channel 0 input.
	C1IN+	AN	—	Comparator C1 positive input.
	ICSPDAT	TTL	CMOS	ICSP™ Data I/O.
	ULPWU	AN	—	Ultra Low-Power Wake-up input.
RA1/AN1/C12IN0-/VREF/ICSPCLK	RA1	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN1	AN	—	A/D Channel 1 input.
	C12IN0-	AN	—	Comparator C1 or C2 negative input.
	VREF	AN	—	External Voltage Reference for A/D.
	ICSPCLK	ST	—	ICSP™ clock.
RA2/AN2/T0CKI/INT/C1OUT	RA2	ST	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN2	AN	—	A/D Channel 2 input.
	T0CKI	ST	—	Timer0 clock input.
	INT	ST	—	External interrupt pin.
	C1OUT	—	CMOS	Comparator C1 output.
RA3/$\overline{\text{MCLR}}$/VPP	RA3	TTL	—	General purpose input. Individually controlled interrupt-on-change.
	$\overline{\text{MCLR}}$	ST	—	Master Clear with internal pull-up.
	VPP	HV	—	Programming voltage.
RA4/AN3/$\overline{\text{T1G}}$/OSC2/CLKOUT	RA4	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN3	AN	—	A/D Channel 3 input.
	$\overline{\text{T1G}}$	ST	—	Timer1 gate input.
	OSC2	—	XTAL	Crystal/Resonator.
	CLKOUT	—	CMOS	FOSC/4 output.
RA5/T1CKI/OSC1/CLKIN	RA5	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	T1CKI	ST	—	Timer1 clock input.
	OSC1	XTAL	—	Crystal/Resonator.
	CLKIN	ST	—	External clock input/RC oscillator connection.
RB4/AN10	RB4	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN10	AN	—	A/D Channel 10 input.
RB5/AN11	RB5	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN11	AN	—	A/D Channel 11 input.
RB6	RB6	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
RB7	RB7	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
RC0/AN4/C2IN+	RC0	ST	CMOS	General purpose I/O.
	AN4	AN	—	A/D Channel 4 input.
	C2IN+	AN	—	Comparator C2 positive input.

Legend: AN = Analog input or output CMOS=CMOS compatible input or output
TTL = TTL compatible input ST= Schmitt Trigger input with CMOS levels
HV = High Voltage XTAL= Crystal

2.2.2.3 INTCON Register

The INTCON register, shown in Register 2-3, is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, PORTA change and external RA2/AN2/T0CKI/INT/C1OUT pin interrupts.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-3: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	T0IE	INTE	RABIE(1,3)	T0IF(2)	INTF	RABIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5 **T0IE:** Timer0 Overflow Interrupt Enable bit
1 = Enables the Timer0 interrupt
0 = Disables the Timer0 interrupt

bit 4 **INTE:** RA2/INT External Interrupt Enable bit
1 = Enables the RA2/INT external interrupt
0 = Disables the RA2/INT external interrupt

bit 3 **RABIE:** PORTA/PORTB Change Interrupt Enable bit(1,3)
1 = Enables the PORTA/PORTB change interrupt
0 = Disables the PORTA/PORTB change interrupt

bit 2 **T0IF:** Timer0 Overflow Interrupt Flag bit(2)
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INTF:** RA2/INT External Interrupt Flag bit
1 = The RA2/INT external interrupt occurred (must be cleared in software)
0 = The RA2/INT external interrupt did not occur

bit 0 **RABIF:** PORTA/PORTB Change Interrupt Flag bit
1 = When at least one of the PORTA or PORTB general purpose I/O pins changed state (must be cleared in software)
0 = None of the PORTA or PORTB general purpose I/O pins have changed state

Note 1: IOCA or IOCB register must also be enabled.
2: T0IF bit is set when Timer0 rolls over. Timer0 is unchanged on Reset and should be initialized before clearing T0IF bit.
3: Includes ULPWU interrupt.

2.2.2.7 PIR2 Register

The PIR2 register contains the interrupt flag bits, as shown in Register 2-7.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-7: PIR2: PERIPHERAL INTERRUPT REQUEST REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
OSFIF	C2IF	C1IF	EEIF	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **OSFIF:** Oscillator Fail Interrupt Flag bit
1 = System oscillator failed, clock input has changed to INTOSC (must be cleared in software)
0 = System clock operating

bit 6 **C2IF:** Comparator C2 Interrupt Flag bit
1 = Comparator output (C2OUT bit) has changed (must be cleared in software)
0 = Comparator output (C2OUT bit) has not changed

bit 5 **C1IF:** Comparator C1 Interrupt Flag bit
1 = Comparator output (C1OUT bit) has changed (must be cleared in software)
0 = Comparator output (C1OUT bit) has not changed

bit 4 **EEIF:** EE Write Operation Interrupt Flag bit
1 = Write operation completed (must be cleared in software)
0 = Write operation has not completed or has not started

bit 3-0 **Unimplemented:** Read as ‘0’

3.2 Oscillator Control

The Oscillator Control (OSCCON) register (Figure 3-1) controls the system clock and frequency selection options. The OSCCON register contains the following bits:

- Frequency selection bits (IRCF)
- Frequency Status bits (HTS, LTS)
- System clock control bits (OSTS, SCS)

REGISTER 3-1: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R/W-1	R/W-1	R/W-0	R-1	R-0	R-0	R/W-0
—	IRCF2	IRCF1	IRCF0	OSTS(1)	HTS	LTS	SCS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **IRCF<2:0>:** Internal Oscillator Frequency Select bits
111 = 8 MHz
110 = 4 MHz (default)
101 = 2 MHz
100 = 1 MHz
011 = 500 kHz
010 = 250 kHz
001 = 125 kHz
000 = 31 kHz (LFINTOSC)

bit 3 **OSTS:** Oscillator Start-up Time-out Status bit(1)
1 = Device is running from the clock defined by FOSC<2:0> of the CONFIG register
0 = Device is running from the internal oscillator (HFINTOSC or LFINTOSC)

bit 2 **HTS:** HFINTOSC Status bit (High Frequency – 8 MHz to 125 kHz)
1 = HFINTOSC is stable
0 = HFINTOSC is not stable

bit 1 **LTS:** LFINTOSC Stable bit (Low Frequency – 31 kHz)
1 = LFINTOSC is stable
0 = LFINTOSC is not stable

bit 0 **SCS:** System Clock Select bit
1 = Internal oscillator is used for system clock
0 = Clock source defined by FOSC<2:0> of the CONFIG register

Note 1: Bit resets to ‘0’ with Two-Speed Start-up and LP, XT or HS selected as the Oscillator mode or Fail-Safe mode is enabled.

3.6 Clock Switching

The system clock source can be switched between external and internal clock sources via software using the System Clock Select (SCS) bit of the OSCCON register.

3.6.1 SYSTEM CLOCK SELECT (SCS) BIT

The System Clock Select (SCS) bit of the OSCCON register selects the system clock source that is used for the CPU and peripherals.

- When the SCS bit of the OSCCON register = 0, the system clock source is determined by configuration of the FOSC<2:0> bits in the Configuration Word register (CONFIG).
- When the SCS bit of the OSCCON register = 1, the system clock source is chosen by the internal oscillator frequency selected by the IRCF<2:0> bits of the OSCCON register. After a Reset, the SCS bit of the OSCCON register is always cleared.

Note:	Any automatic clock switch, which may occur from Two-Speed Start-up or Fail-Safe Clock Monitor, does not update the SCS bit of the OSCCON register. The user can monitor the OSTS bit of the OSCCON register to determine the current system clock source.

3.6.2 OSCILLATOR START-UP TIME-OUT STATUS (OSTS) BIT

The Oscillator Start-up Time-out Status (OSTS) bit of the OSCCON register indicates whether the system clock is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Word register (CONFIG), or from the internal clock source. In particular, OSTS indicates that the Oscillator Start-up Timer (OST) has timed out for LP, XT or HS modes.

3.7 Two-Speed Clock Start-up Mode

Two-Speed Start-up mode provides additional power savings by minimizing the latency between external oscillator start-up and code execution. In applications that make heavy use of the Sleep mode, Two-Speed Start-up will remove the external oscillator start-up time from the time spent awake and can reduce the overall power consumption of the device.

This mode allows the application to wake-up from Sleep, perform a few instructions using the INTOSC as the clock source and go back to Sleep without waiting for the primary oscillator to become stable.

Note:	Executing a SLEEP instruction will abort the oscillator start-up time and will cause the OSTS bit of the OSCCON register to remain clear.

When the Oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) is enabled (see **Section 3.4.1 "Oscillator Start-up Timer (OST)"**). The OST will suspend program execution until 1024 oscillations are counted. Two-Speed Start-up mode minimizes the delay in code execution by operating from the internal oscillator as the OST is counting. When the OST count reaches 1024 and the OSTS bit of the OSCCON register is set, program execution switches to the external oscillator.

3.7.1 TWO-SPEED START-UP MODE CONFIGURATION

Two-Speed Start-up mode is configured by the following settings:

- IESO (of the Configuration Word register) = 1; Internal/External Switchover bit (Two-Speed Start-up mode enabled).
- SCS (of the OSCCON register) = 0.
- FOSC<2:0> bits in the Configuration Word register (CONFIG) configured for LP, XT or HS mode.

Two-Speed Start-up mode is entered after:

- Power-on Reset (POR) and, if enabled, after Power-up Timer (PWRT) has expired, or
- Wake-up from Sleep.

If the external clock oscillator is configured to be anything other than LP, XT or HS mode, then Two-speed Start-up is disabled. This is because the external clock oscillator does not require any stabilization time after POR or an exit from Sleep.

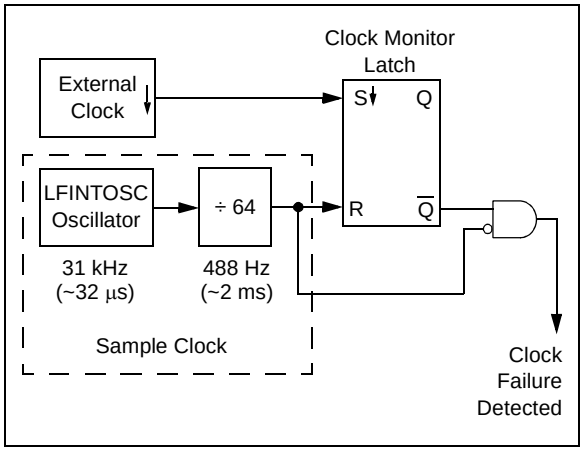
3.7.2 TWO-SPEED START-UP SEQUENCE

1. Wake-up from Power-on Reset or Sleep.
2. Instructions begin execution by the internal oscillator at the frequency set in the IRCF<2:0> bits of the OSCCON register.
3. OST enabled to count 1024 clock cycles.
4. OST timed out, wait for falling edge of the internal oscillator.
5. OSTS is set.
6. System clock held low until the next falling edge of new clock (LP, XT or HS mode).
7. System clock is switched to external clock source.

3.8 Fail-Safe Clock Monitor

The Fail-Safe Clock Monitor (FSCM) allows the device to continue operating should the external oscillator fail. The FSCM can detect oscillator failure any time after the Oscillator Start-up Timer (OST) has expired. The FSCM is enabled by setting the FCMEN bit in the Configuration Word register (CONFIG). The FSCM is applicable to all external Oscillator modes (LP, XT, HS, EC, RC and RCIO).

FIGURE 3-8: FSCM BLOCK DIAGRAM



3.8.1 FAIL-SAFE DETECTION

The FSCM module detects a failed oscillator by comparing the external oscillator to the FSCM sample clock. The sample clock is generated by dividing the LFINTOSC by 64. See Figure 3-8. Inside the fail detector block is a latch. The external clock sets the latch on each falling edge of the external clock. The sample clock clears the latch on each rising edge of the sample clock. A failure is detected when an entire half-cycle of the sample clock elapses before the primary clock goes low.

3.8.2 FAIL-SAFE OPERATION

When the external clock fails, the FSCM switches the device clock to an internal clock source and sets the bit flag OSFIF of the PIR2 register. Setting this flag will generate an interrupt if the OSFIE bit of the PIE2 register is also set. The device firmware can then take steps to mitigate the problems that may arise from a failed clock. The system clock will continue to be sourced from the internal clock source until the device firmware successfully restarts the external oscillator and switches back to external operation.

The internal clock source chosen by the FSCM is determined by the IRCF<2:0> bits of the OSCCON register. This allows the internal oscillator to be configured before a failure occurs.

3.8.3 FAIL-SAFE CONDITION CLEARING

The Fail-Safe condition is cleared after a Reset, executing a SLEEP instruction or toggling the SCS bit of the OSCCON register. When the SCS bit is toggled, the OST is restarted. While the OST is running, the device continues to operate from the INTOSC selected in OSCCON. When the OST times out, the Fail-Safe condition is cleared and the device will be operating from the external clock source. The Fail-Safe condition must be cleared before the OSFIF flag can be cleared.

3.8.4 RESET OR WAKE-UP FROM SLEEP

The FSCM is designed to detect an oscillator failure after the Oscillator Start-up Timer (OST) has expired. The OST is used after waking up from Sleep and after any type of Reset. The OST is not used with the EC or RC Clock modes so that the FSCM will be active as soon as the Reset or wake-up has completed. When the FSCM is enabled, the Two-Speed Start-up is also enabled. Therefore, the device will always be executing code while the OST is operating.

Note:	Due to the wide range of oscillator start-up times, the Fail-Safe circuit is not active during oscillator start-up (i.e., after exiting Reset or Sleep). After an appropriate amount of time, the user should check the OSTS bit of the OSCCON register to verify the oscillator start-up and that the system clock switchover has successfully completed.

TABLE 4-1: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ADCON0	ADFM	VCFG	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	0000 0000	0000 0000
ANSEL	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
CM1CON0	C1ON	C1OUT	C1OE	C1POL	—	C1R	C1CH1	C1CH0	0000 -000	0000 -000
INTCON	GIE	PEIE	T0IE	INTE	RABIE	T0IF	INTF	RABIF	0000 000x	0000 000x
IOCA	—	—	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0	--00 0000	--00 0000
OPTION_REG	$\overline{\text{RABPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--xx xxxx	--uu uuuu
SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
T1CON	T1GINV	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	0000 0000	uuuu uuuu
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	--11 1111
WPUA	—	—	WPUA5	WPUA4	—	WPUA2	WPUA1	WPUA0	--11 -111	--11 -111

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

9.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESL and ADRESH).

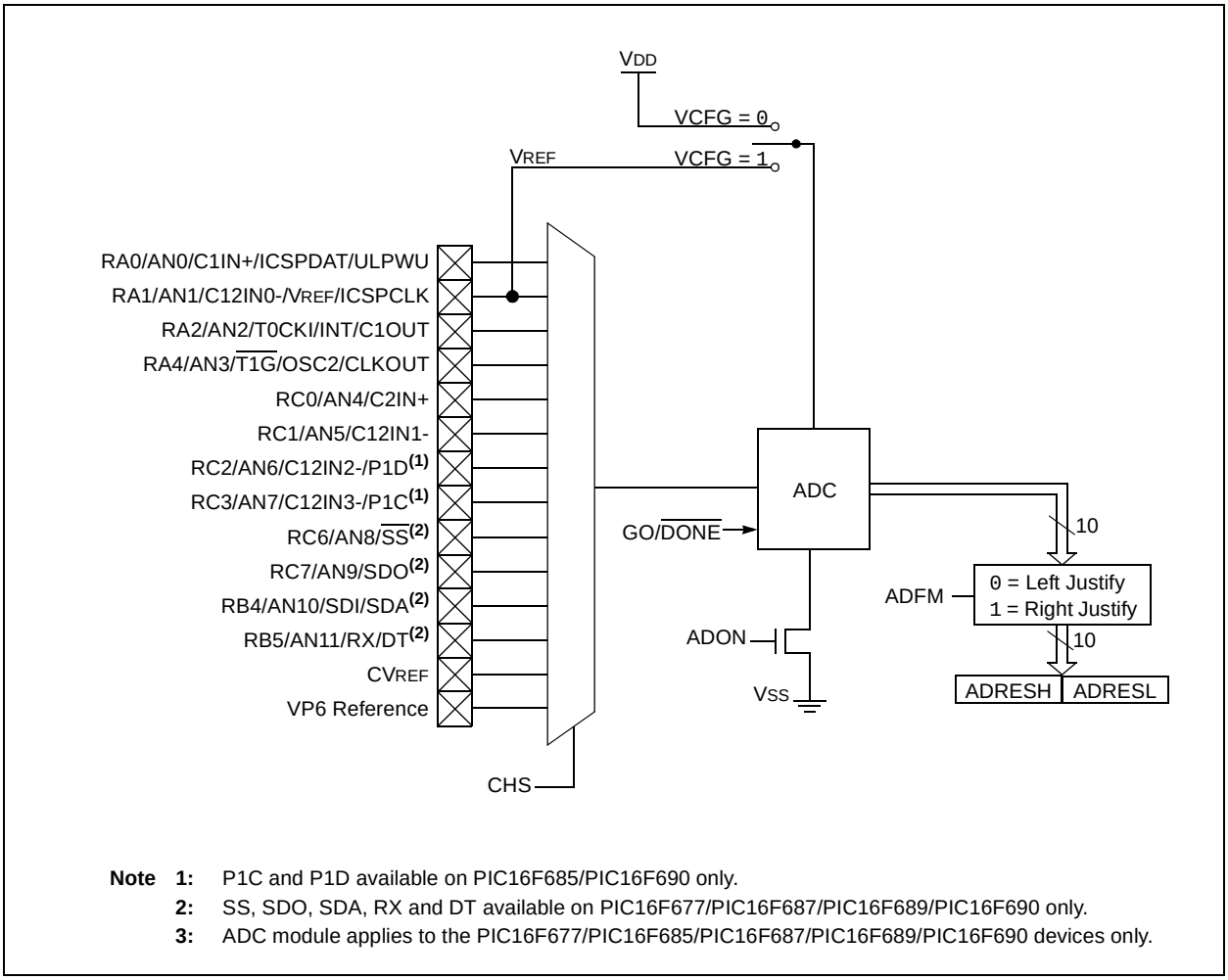
Note:	The ADC module applies to PIC16F677/ PIC16F685/PIC16F687/PIC16F689/ PIC16F690 devices only.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

Figure 9-1 shows the block diagram of the ADC.

FIGURE 9-1: ADC BLOCK DIAGRAM



Note 1: P1C and P1D available on PIC16F685/PIC16F690 only.
2: SS, SDO, SDA, RX and DT available on PIC16F677/PIC16F687/PIC16F689/PIC16F690 only.
3: ADC module applies to the PIC16F677/PIC16F685/PIC16F687/PIC16F689/PIC16F690 devices only.

TABLE 9-2: SUMMARY OF ASSOCIATED ADC REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ADCON0	ADFM	VCFG	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	0000 0000	0000 0000
ADCON1	—	ADCS2	ADCS1	ADCS0	—	—	—	—	-000 ----	-000 ----
ANSEL	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
ANSELH	—	—	—	—	ANS11	ANS10	ANS9	ANS8	---- 1111	---- 1111
ADRESH	A/D Result Register High Byte								xxxx xxxx	uuuu uuuu
ADRESL	A/D Result Register Low Byte								xxxx xxxx	uuuu uuuu
INTCON	GIE	PEIE	T0IE	INTE	RABIE	T0IF	INTF	RABIF	0000 000x	0000 000x
PIE1	—	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	-000 0000	-000 0000
PIR1	—	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--xx xxxx	--uu uuuu
PORTB	RB7	RB6	RB5	RB4	—	—	—	—	xxxx ----	uuuu ----
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	--11 1111
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	—	—	—	—	1111 ----	1111 ----
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged, – = unimplemented read as '0'. Shaded cells are not used for ADC module.

TABLE 12-5: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 11.0592 MHz			FOSC = 8.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	1221	1.73	255	1200	0.00	239	1200	0.00	143	1202	0.16	103
2400	2404	0.16	129	2400	0.00	119	2400	0.00	71	2404	0.16	51
9600	9470	-1.36	32	9600	0.00	29	9600	0.00	17	9615	0.16	12
10417	10417	0.00	29	10286	-1.26	27	10165	-2.42	16	10417	0.00	11
19.2k	19.53k	1.73	15	19.20k	0.00	14	19.20k	0.00	8	—	—	—
57.6k	—	—	—	57.60k	0.00	7	57.60k	0.00	2	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300	0.16	207	300	0.00	191	300	0.16	103	300	0.16	51
1200	1202	0.16	51	1200	0.00	47	1202	0.16	25	1202	0.16	12
2400	2404	0.16	25	2400	0.00	23	2404	0.16	12	—	—	—
9600	—	—	—	9600	0.00	5	—	—	—	—	—	—
10417	10417	0.00	5	—	—	—	10417	0.00	2	—	—	—
19.2k	—	—	—	19.20k	0.00	2	—	—	—	—	—	—
57.6k	—	—	—	57.60k	0.00	0	—	—	—	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 11.0592 MHz			FOSC = 8.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	—	—	—	—	—	—	—	—	—
2400	—	—	—	—	—	—	—	—	—	2404	0.16	207
9600	9615	0.16	129	9600	0.00	119	9600	0.00	71	9615	0.16	51
10417	10417	0.00	119	10378	-0.37	110	10473	0.53	65	10417	0.00	47
19.2k	19.23k	0.16	64	19.20k	0.00	59	19.20k	0.00	35	19231	0.16	25
57.6k	56.82k	-1.36	21	57.60k	0.00	19	57.60k	0.00	11	55556	-3.55	8
115.2k	113.64k	-1.36	10	115.2k	0.00	9	115.2k	0.00	5	—	—	—

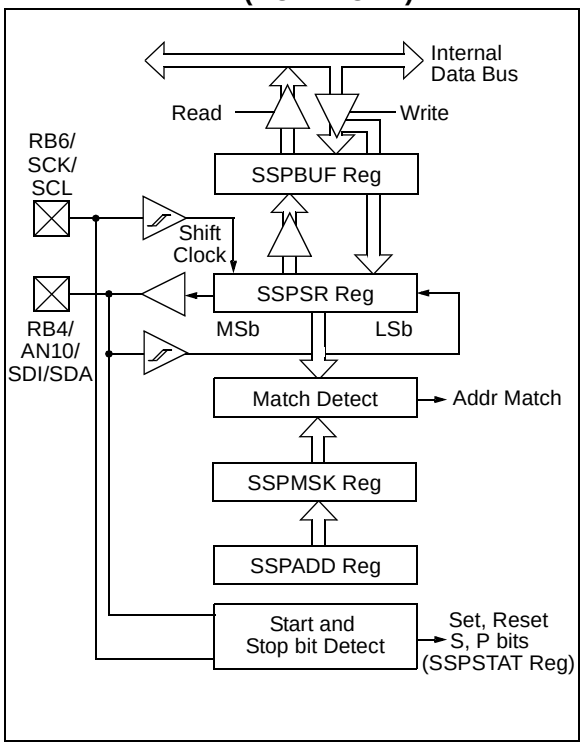
13.11 SSP I²C Operation

The SSP module in I²C mode, fully implements all slave functions, except general call support, and provides interrupts on Start and Stop bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the Standard mode specifications, as well as 7-bit and 10-bit addressing.

Two pins are used for data transfer. These are the RB6/SCK/SCL pin, which is the clock (SCL), and the RB4/AN10/SDI/SDA pin, which is the data (SDA).

The SSP module functions are enabled by setting SSP enable bit SSPEN (SSPCON<5>).

FIGURE 13-7: SSP BLOCK DIAGRAM (I²C™ MODE)



The SSP module has six registers for the I²C operation, which are listed below.

- SSP Control register (SSPCON)
- SSP Status register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift register (SSPSR) – Not directly accessible
- SSP Address register (SSPADD)
- SSP Mask register (SSPMSK)

The SSPCON register allows control of the I²C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I²C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Slave mode (7-bit address), with Start and Stop bit interrupts enabled to support Firmware Master mode
- I²C Slave mode (10-bit address), with Start and Stop bit interrupts enabled to support Firmware Master mode
- I²C Start and Stop bit interrupts enabled to support Firmware Master mode; Slave is idle

Selection of any I²C mode with the SSPEN bit set forces the SCL and SDA pins to be open drain, provided these pins are programmed to inputs by setting the appropriate TRISB bits. Pull-up resistors must be provided externally to the SCL and SDA pins for proper operation of the I²C module.

13.12 Slave Mode

In Slave mode, the SCL and SDA pins must be configured as inputs (TRISB<6,4> are set). The SSP module will override the input state with the output data when required (slave-transmitter).

When an address is matched, or the data transfer after an address match is received, the hardware automatically will generate the Acknowledge ($\overline{ACK}$) pulse, and then load the SSPBUF register with the received value currently in the SSPSR register.

There are certain conditions that will cause the SSP module not to give this $\overline{ACK}$ pulse. They include (either or both):

a) The Buffer Full bit BF of the SSPSTAT register was set before the transfer was received.

b) The overflow bit SSPOV of the SSPCON register was set before the transfer was received.

In this case, the SSPSR register value is not loaded into the SSPBUF, but bit SSPIF of the PIR1 register is set. Table 13-3 shows the results of when a data transfer byte is received, given the status of bits BF and SSPOV. The shaded cells show the condition where user software did not properly clear the overflow condition. Flag bit BF is cleared by reading the SSPBUF register, while bit SSPOV is cleared through software.

The SCL clock input must have a minimum high and low for proper operation. For high and low times of the I²C specification, as well as the requirements of the SSP module, see **Section 17.0 "Electrical Specifications"**.

14.0 SPECIAL FEATURES OF THE CPU

The PIC16F631/677/685/687/689/690 have a host of features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving features and offer code protection.

These features are:

- Reset
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- Oscillator selection
- Sleep
- Code protection
- ID Locations
- In-Circuit Serial Programming

The PIC16F631/677/685/687/689/690 have two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 64 ms (nominal) on power-up only, designed to keep the part in Reset while the power supply stabilizes. There is also circuitry to reset the device if a brown-out occurs, which can use the Power-up Timer to provide at least a 64 ms Reset. With these three functions-on-chip, most applications need no external Reset circuitry.

The Sleep mode is designed to offer a very low-current Power-down mode. The user can wake-up from Sleep through:

- External Reset
- Watchdog Timer Wake-up
- An interrupt

Several oscillator options are also made available to allow the part to fit the application. The INTOSC option saves system cost while the LP crystal option saves power. A set of Configuration bits are used to select various options (see Register 14-2).

14.1 Configuration Bits

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1') to select various device configurations as shown in Register 14-2. These bits are mapped in program memory location 2007h.

Note:	Address 2007h is beyond the user program memory space. It belongs to the special configuration memory space (2000h-3FFFh), which can be accessed only during programming. See *"PIC12F6XX/16F6XX Memory Programming Specification"* (DS41204) for more information.

14.6 Power-Down Mode (Sleep)

The Power-Down mode is entered by executing a SLEEP instruction.

If the Watchdog Timer is enabled:

- WDT will be cleared but keeps running.
- $\overline{PD}$ bit in the STATUS register is cleared.
- $\overline{TO}$ bit is set.
- Oscillator driver is turned off.
- I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD} or V_{SS}, with no external circuitry drawing current from the I/O pin and the comparators and CV_{REF} should be disabled. I/O pins that are high-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTA should be considered.

The $\overline{MCLR}$ pin must be at a logic high level.

Note:	It should be noted that a Reset generated by a WDT time-out does not drive $\overline{MCLR}$ pin low.

14.6.1 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from RA2/INT pin, PORTA change or a peripheral interrupt.

The first event will cause a device Reset. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device Reset. The $\overline{PD}$ bit, which is set on power-up, is cleared when Sleep is invoked. $\overline{TO}$ bit is cleared if WDT Wake-up occurred.

The following peripheral interrupts can wake the device from Sleep:

1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
2. ECCP Capture mode interrupt.
3. A/D conversion (when A/D clock source is FRC).
4. EEPROM write operation completion.
5. Comparator output changes state.
6. Interrupt-on-change.
7. External Interrupt from INT pin.
8. EUSART Break detect, I^2C slave.

Other peripherals cannot generate interrupts since during Sleep, no on-chip clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up occurs regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction, then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from Sleep. The SLEEP instruction is completely executed.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

14.6.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will not be cleared, the $\overline{TO}$ bit will not be set and the $\overline{PD}$ bit will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

15.0 INSTRUCTION SET SUMMARY

The PIC16F690 instruction set is highly orthogonal and is comprised of three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

Each PIC16 instruction is a 14-bit word divided into an **opcode,** which specifies the instruction type and one or more **operands,** which further specify the operation of the instruction. The formats for each of the categories is presented in Figure 15-1, while the various opcode fields are summarized in Table 15-1.

Table 15-2 lists the instructions recognized by the MPASM™ assembler.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator, which selects the bit affected by the operation, while 'f' represents the address of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8-bit or 11-bit constant, or literal value.

One instruction cycle consists of four oscillator periods; for an oscillator frequency of 4 MHz, this gives a normal instruction execution time of 1 μs. All instructions are executed within a single instruction cycle, unless a conditional test is true, or the program counter is changed as a result of an instruction. When this occurs, the execution takes two instruction cycles, with the second cycle executed as a NOP.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

15.1 Read-Modify-Write Operations

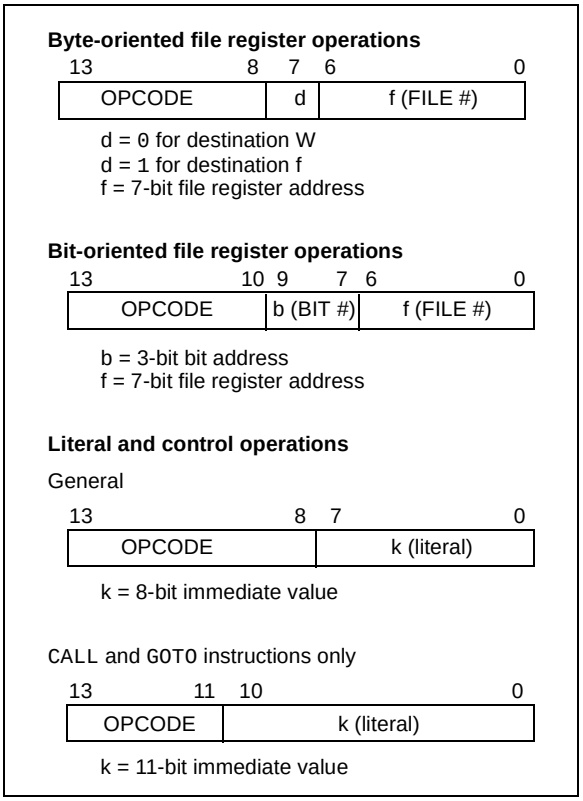
Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (RMW) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register.

For example, a CLRF PORTA instruction will read PORTA, clear all the data bits, then write the result back to PORTA. This example would have the unintended consequence of clearing the condition that set the RAIF flag.

TABLE 15-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1.
PC	Program Counter
$\overline{TO}$	Time-out bit
C	Carry bit
DC	Digit carry bit
Z	Zero bit
$\overline{PD}$	Power-down bit

FIGURE 15-1: GENERAL FORMAT FOR INSTRUCTIONS



17.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40° to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.5V
Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +13.5V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA
Output clamp current, I_{OK} (Vo < 0 or Vo >V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA, PORTB and PORTC (combined) ..... 200 mA
Maximum current sourced PORTA, PORTB and PORTC (combined) ..... 200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a “low” level to the $\overline{MCLR}$ pin, rather than pulling this pin directly to V_{SS}.

17.2 DC Characteristics: PIC16F631/677/685/687/689/690-I (Industrial) PIC16F631/677/685/687/689/690-E (Extended)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						VDD	Note
D010	**Supply Current (IDD)(1, 2)**	—	13	19	µA	2.0	FOSC = 32 kHz LP Oscillator mode
		—	22	30	µA	3.0	
		—	33	60	µA	5.0	
D011*		—	140	240	µA	2.0	FOSC = 1 MHz XT Oscillator mode
		—	220	380	µA	3.0	
		—	380	550	µA	5.0	
D012		—	260	360	µA	2.0	FOSC = 4 MHz XT Oscillator mode
		—	420	650	µA	3.0	
		—	0.8	1.1	mA	5.0	
D013*		—	130	220	µA	2.0	FOSC = 1 MHz EC Oscillator mode
		—	215	360	µA	3.0	
		—	360	520	µA	5.0	
D014		—	220	340	µA	2.0	FOSC = 4 MHz EC Oscillator mode
		—	375	550	µA	3.0	
		—	0.65	1.0	mA	5.0	
D015		—	8	20	µA	2.0	FOSC = 31 kHz LFINTOSC mode
		—	16	40	µA	3.0	
		—	31	65	µA	5.0	
D016*		—	340	450	µA	2.0	FOSC = 4 MHz HFINTOSC mode
		—	500	700	µA	3.0	
		—	0.8	1.2	mA	5.0	
D017		—	410	650	µA	2.0	FOSC = 8 MHz HFINTOSC mode
		—	700	950	µA	3.0	
		—	1.30	1.65	mA	5.0	
D018		—	230	400	µA	2.0	FOSC = 4 MHz EXTRC mode(3)
		—	400	680	µA	3.0	
		—	0.63	1.1	mA	5.0	
D019		—	3.8	5.0	mA	4.5	FOSC = 20 MHz HS Oscillator mode
		—	4.0	5.45	mA	5.0	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

4: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

5: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.

TABLE 17-19: DC CHARACTERISTICS FOR IDD SPECIFICATIONS FOR PIC16F685/687/689/690-H (High Temp.)

Param No.	Device Characteristics	Min.	Typ.	Max.	Units	Condition	
						VDD	Note
D001	VDD	2.1	—	5.5	V	—	FOSC ≤ 8 MHz: HFINTOSC, EC
		2.1	—	5.5	V	—	FOSC ≤ 4 MHz
D010	Supply Current (IDD)	—	—	47	μA	2.1	Fosc = 32 kHz LP Oscillator
		—	—	69		3.0	
		—	—	108		5.0	
D011		—	—	357	μA	2.1	Fosc = 1 MHz XT Oscillator
		—	—	533		3.0	
		—	—	729		5.0	
D012		—	—	535	μA	2.1	Fosc = 4 MHz XT Oscillator
		—	—	875		3.0	
		—	—	1.32	mA	5.0	
D013		—	—	336	μA	2.1	Fosc = 1 MHz EC Oscillator
		—	—	477		3.0	
		—	—	777		5.0	
D014		—	—	505	μA	2.1	Fosc = 4 MHz EC Oscillator
		—	—	724		3.0	
		—	—	1.30	mA	5.0	
D015		—	—	51	μA	2.1	Fosc = 31 kHz LFINTOSC
		—	—	92		3.0	
		—	—	117	mA	5.0	
D016		—	—	665	μA	2.1	Fosc = 4 MHz HFINTOSC
		—	—	970		3.0	
		—	—	1.56	mA	5.0	
D017		—	—	936	μA	2.1	Fosc = 8 MHz HFINTOSC
		—	—	1.34	mA	3.0	
		—	—	2.27		5.0	
D018		—	—	605	μA	2.1	Fosc = 4 MHz EXTRC
		—	—	903		3.0	
		—	—	1.43	mA	5.0	
D019		—	—	6.61	mA	4.5	Fosc = 20 MHz HS Oscillator
		—	—	7.81		5.0	

18.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

The graphs and tables provided in this section are for **design guidance** and are **not tested**.

In some graphs or tables, the data presented are **outside specified operating range** (i.e., outside specified V_{DD} range). This is for **information only** and devices are ensured to operate properly only within the specified range.

Note:	The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over each temperature range.

FIGURE 18-1: TYPICAL I_{DD} vs. F_{OSC} OVER V_{DD} (EC MODE)